

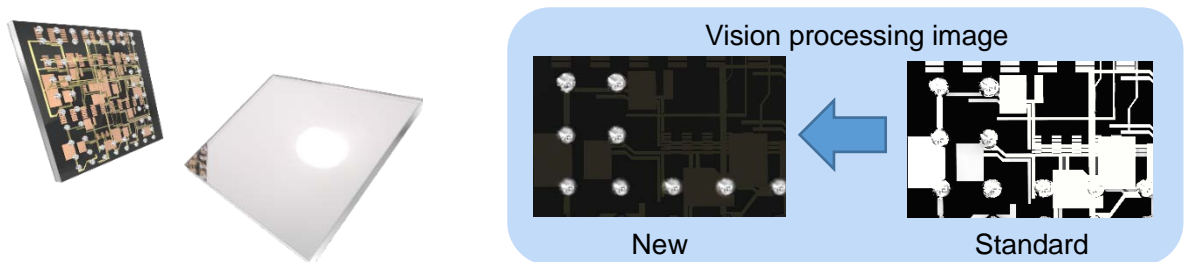
## Fuji placement solutions for manufacturing smaller and more advanced module parts

Fuji Corporation (headquarters: Chiryu, Aichi; president & CEO: Mr. Nobuyuki Soga) has developed a new function suitable for manufacturing module parts.

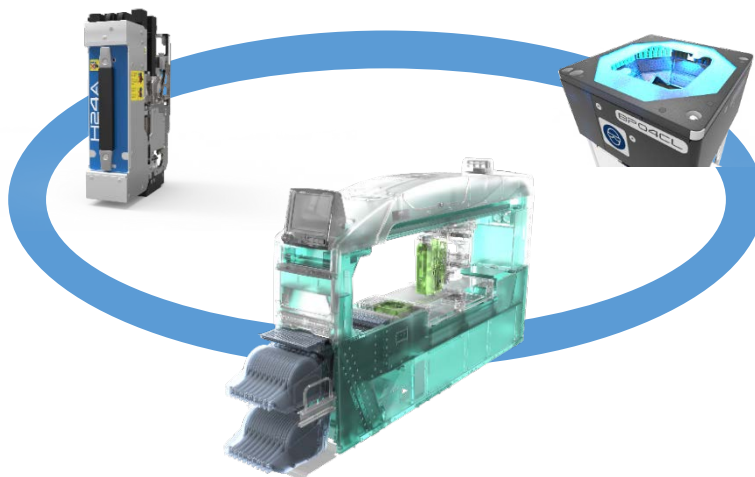
Along with the spread of mobile devices and wearable devices, the demand for module parts used in these products has been increasing.

As module parts are smaller, lighter, and more advanced, parts composing those module parts follow the same trend as well.

There is a growing need to support these new parts and efficiently produce them at production sites. On the other hand, there are some problems to be solved. For example, when placing parts such as System in Package (SiP) or Wafer level Chip Size Package (WLCSP) parts, the bump positions could not be detected correctly when vision processing.



To deal with this problem, Fuji has successfully developed a technology by improving the vision processing camera. It is now possible to acquire an image of bumps alone without reflecting the circuits of SiP and WLCSP. Furthermore, by combining units and functions that are effective for manufacturing module parts, including placement modules (M3IIIS), heads (H24A), a dipping unit, a nozzle with a slit, and vacuum backup, we can propose solutions for high quality placement of module parts that enhances productivity.



Contact your Fuji representative for details on our products.